**TO-3P** 

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# N-Channel 100-V (D-S) MOSFET

PRODUCT	SUMMARY	
V <sub>(BR)DSS</sub> (V)	$r_{DS(on)}(\Omega)$	I <sub>D</sub> (A)
100	0.018 at V <sub>GS</sub> = 10 V	65 <sup>a</sup>

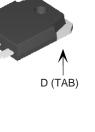
### **FEATURES**

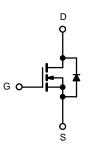
- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R<sub>g</sub> Tested



## **APPLICATIONS**

• Isolated DC/DC Converters





N-Channel MOSFET

ABSOLUTE MAXIMUM RATING	<b>S</b> $T_C = 25  ^{\circ}C$ , unless oth	erwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20		
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>C</sub> = 25 °C		65 <sup>a</sup>	^	
	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	31 <sup>a</sup>		
Pulsed Drain Current		I <sub>DM</sub>	140	A	
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	31	1	
Single Pulse Avalanche Energy <sup>b</sup>	L = 0.111111	E <sub>AS</sub>	60	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	В	355 <sup>c</sup>	W	
	T <sub>A</sub> = 25 °C <sup>d</sup>	P <sub>D</sub>	3.35		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS				
Parameter		Symbol	Limit	Unit
Junction-to-Ambient	PCB Mount	R <sub>thJA</sub>	40	°C/W
unction-to-Case (Drain)		R <sub>thJC</sub>	0.4	C/VV

#### Notes:

- a. Package limited.
- b. Duty cycle  $\leq$  1 %.
- c. See SOA curve for voltage derating.
- d. When Mounted on 1" square PCB (FR-4 material).



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	100			V
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2		4	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V			1	μΑ
	I <sub>DSS</sub>	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		0.018		Ω
	r <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C		0.023		
		$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}, T_J = 175 ^{\circ}\text{C}$		0.037		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 30 \text{ A}$	25			S
Dynamic <sup>b</sup>	•					
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		3200		pF
Output Capacitance	C <sub>oss</sub>			410		
Reverse Transfer Capacitance	C <sub>rss</sub>			210		
Total Gate Charge <sup>c</sup>	$Q_g$			90	130	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 58 \text{ A}$		23		
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			34		
Gate Resistance	$R_{g}$		0.5	1.3	3.1	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	$V_{DD}$ = 100 V, $R_L$ = 1.5 $\Omega$ $I_D \cong 58$ A, $V_{GEN}$ = 10 V, $R_g$ = 2.5 $\Omega$		24	35	ns
Rise Time <sup>c</sup>	t <sub>r</sub>			220	330	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			45	70	
Fall Time <sup>c</sup>	t <sub>f</sub>			200	300	
Source-Drain Diode Ratings and Ch	aracteristics 7	T <sub>C</sub> = 25 °C <sup>b</sup>				
Continuous Current	I <sub>S</sub>				58	A
Pulsed Current	I <sub>SM</sub>				110	
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = 58 A, V <sub>GS</sub> = 0 V		1.0	1.5	V
Reverse Recovery Time	t <sub>rr</sub>			130	200	ns
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 30 A, di/dt = 100 A/μs		8	12	Α
Reverse Recovery Charge	Q <sub>rr</sub>			0.52	1.2	иC

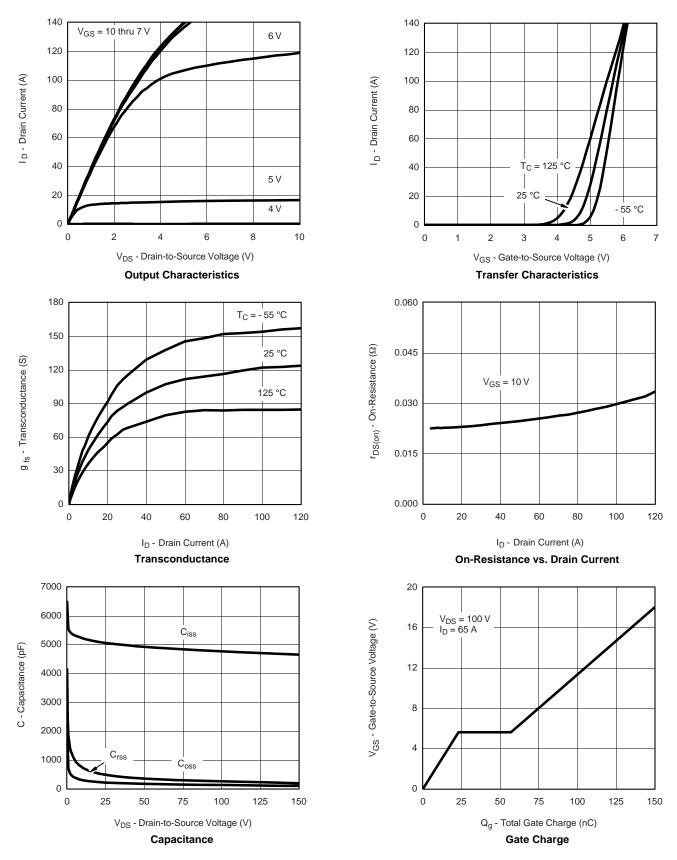
#### Notes:

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

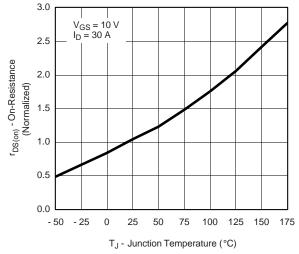


# TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

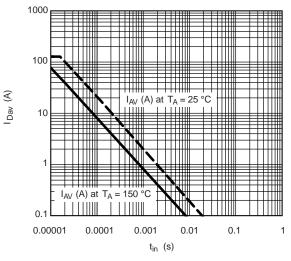




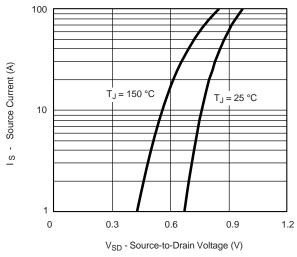
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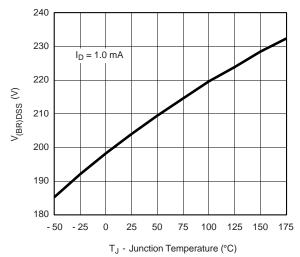
On-Resistance vs. Junction Temperature



Avalanche Current vs. Time



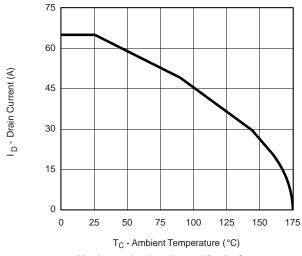
Source-Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



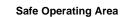
### **THERMAL RATINGS**

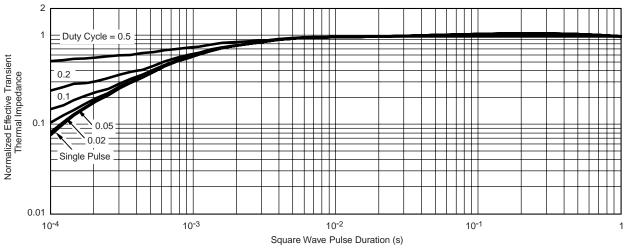


r<sub>DS(on)</sub> Limited 10 µs 100 I<sub>D</sub> - Drain Current (A) 10 T<sub>C</sub> = 25 °C 10 ms 100 ms DC Single Pulse 0.1 0.1 100 1000 10  $V_{DS}$  - Drain-to-Source Voltage (V) \*  $V_{GS}$  > minimum  $V_{GS}$  at which  $r_{DS(on)}$  is specified

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Maximum Avalanche and Drain Current vs. Case Temperature





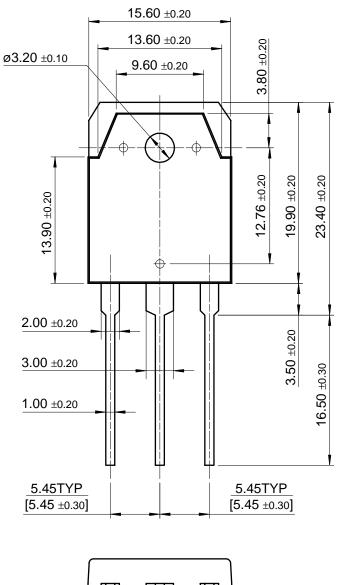
Normalized Thermal Transient Impedance, Junction-to-Case

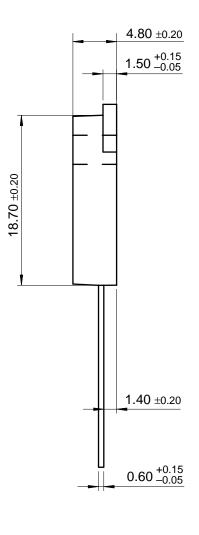
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